

# Semiconductor Equipment Corporation

## Product Catalog



**Models 300 / 3150 / 3100  
Wafer/Frame Tape Applicators**  
Mounts all size wafers and other substrates onto film frames for dicing. More information: <https://bit.ly/3qPoaOo>



**Models 3200 / 3250  
Wafer/Backlap Applicator**  
Applies protective tape to your wafer prior to backlapping. More information: <https://bit.ly/3cavUGR>



**Model 365 UV Exposure System**  
Revolutionary new design cures most UV tapes in 5 seconds! Features a long life light source and handles all size wafers up to 300mm. More info: <https://bit.ly/3qRlfnm>



**Model HS-1810 Die Matrix Expander**  
Semiautomatic system capable of expanding 6" or 8" wafers, which are diced or scribed and mounted on dicing tape and film frame. More info: <https://bit.ly/2Yiz2by>



**Model 4800 Die Ejector Grid**  
Releases die for easy removal from Dicing tape. More information: <https://bit.ly/3pmwftO>



**Model 865 Die Bonder**  
A multi-use windows based system, which can be configured to bond laser bars, laser diodes, flip chip, eutectic bonded die and more. More information: <https://bit.ly/3qMDc7M>



**Model 450 Hot Gas Rework Station**  
Hot gas rework station removes surface mounted components and bonded die. More information: <https://bit.ly/2MmzWB3>



**Model 835 Pick & Place System**  
General purpose pick and place system for die and surface mount components. Transfers die from tape to waffle packs. Epoxy dispense option. More information: <https://bit.ly/3qS2SQo>



**Model 850 Flip Chip Die Bonder**  
A versatile, semi-automatic system for flip chips, chip scale devices and bare die. Good for low volume production. More information: <https://bit.ly/3aaWvKB>



**Model 4750 Die Ejector**  
Pokes die off of dicing tape. Especially useful for small die. More Information: <https://bit.ly/3qRIYoA>



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